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September 2016

FAN49103 — 2.5 A, 1.8 MHz, TinyPower[™] I²C Buck-Boost Regulator

Features

- 24 µA Typical PFM Quiescent Current
- Above 95% Efficiency
- Total Layout Area = 11.61 mm²
- Input Voltage Range: 2.5 V to 5.5 V
- Maximum Continuous Load Current:
 - 3.0 A at V_{OUT}=3.4 V, V_{IN}=3.3 V
 - 2.5 A at V_{OUT}=3.4 V, V_{IN}=3.0 V
 - 2.0 A at V_{OUT}=3.4 V, V_{IN}=2.5 V
- I²C Compatible Interface
- Programmable Output Voltage:
 2.8 V to 4.0 V in 25 mV Steps
- 1.8 MHz Fixed-Frequency Operation in PWM Mode
- Automatic / Seamless Step-up and Step-down Mode Transitions
- Forced PWM and Automatic PFM/PWM Mode Selection
- 0.5 µA Typical Shutdown Current
- Low Quiescent Current Pass-Through Mode
- Internal Soft-Start and Output Discharge
- Low Ripple and Excellent Transient Response
- Internally Set, Automatic Safety Protections (UVLO, OTP, SCP, OCP)
- Package: 20 Bump, 0.4 mm Pitch WLCSP

Applications

- Smart Phones
- Tablets, Netbooks[®], Ultra-Mobile PCs
- Portable Devices with Li-ion Battery
- 2G/3G/4G Power Amplifiers
- NFC Applications

Description

The FAN49103 is a high efficiency buck-boost switching mode regulator which accepts input voltages either above or below the regulated output voltage. Using full-bridge architecture with synchronous rectification, the FAN49103 is capable of delivering up to 2.5 A while regulating the output at 3.4 V. The FAN49103 exhibits seamless transition between step-up and step-down modes reducing output disturbances. The output voltage and operation mode of the regulator can be programmed through an I^2C interface.

At moderate and light loads, Pulse Frequency Modulation (PFM) is used to operate the device in power-save mode to maintain high efficiency. In PFM mode, the part still exhibits excellent transient response during load steps. At moderate to heavier loads or Forced PWM mode, the regulator switches to PWM fixed-frequency control. While in PWM mode, the regulator operates at a nominal fixed frequency of 1.8 MHz, which allows for reduced external component values.

The FAN49103 is available in a 20-bump 1.615 mm x 2.015 mm with 0.4 mm pitch WLCSP.

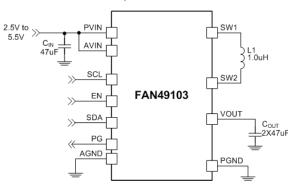
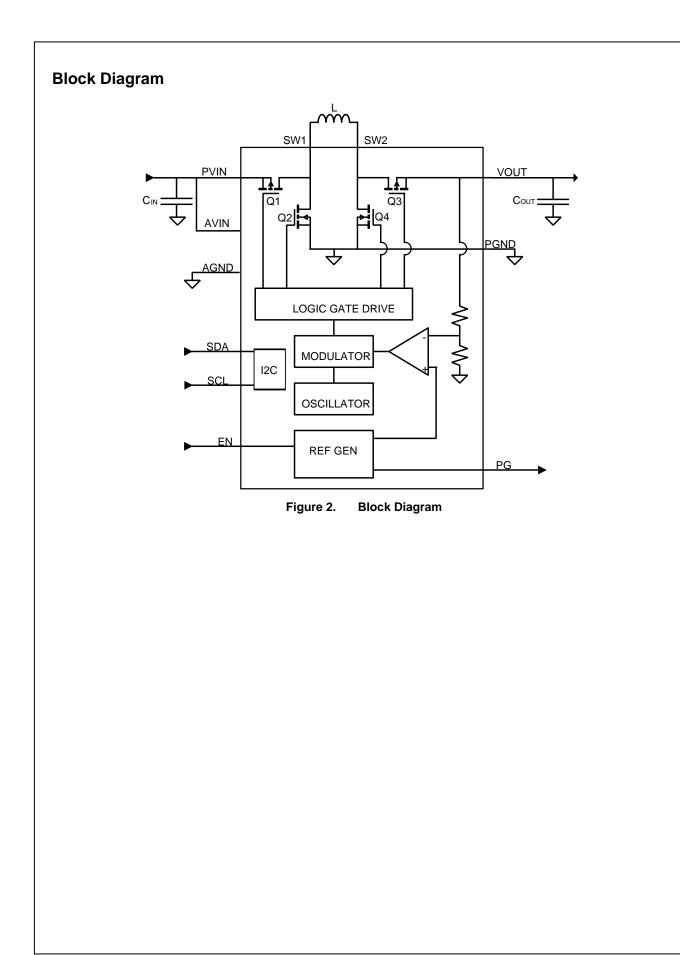


Figure 1. Typical Application

Ordering Informa	ation				
Part Number	Output Discharge	Temperature Range	Package	Packing Method	Device Marking
FAN49103AUC340X	Yes	-40 to 85°C	20-Ball (WLCSP)	Tape and Reel	FC



Pin Configuration

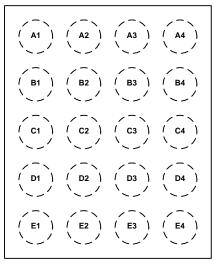


Figure 3. Top View (bump down)

Pin Definitions⁽¹⁾

Pin #	Name	Description
A3, A4	PVIN	Power Input Voltage. Connect to input power source. Connect to C _{IN} with minimal path.
A1	AVIN	Analog Input Voltage. Analog input for device. Connect to C _{IN} and PVIN.
A2	EN	Enable. A HIGH logic level on this pin forces the device to be enabled. A LOW logic level forces the device into shutdown. EN pin can be tied to VIN or driven via a GPIO logic voltage.
B3, B4	SW1	Switching Node 1. Connect to inductor L1.
E1	AGND	Analog Ground. Control block signal is referenced to this pin. Short AGND to PGND at GND pad of C_{OUT} .
B1, C1, C2, C3, C4, D1	PGND	Power Ground. Low-side MOSFET of buck and main MOSFET of boost are referenced to this pin. C_{IN} and C_{OUT} should be returned with a minimal path to these pins.
D2	SDA	I ² C Data Line. Used for I ² C communication.
D3, D4	SW2	Switching Node 2. Connect to inductor L1.
E2	PG	Power Good. This is an open-drain output and normally High Z. An external pull-up resistor from VOUT can be used to generate a logic HIGH. PG is pulled LOW if output falls out of regulation due to current overload or if thermal protection threshold is exceeded. If EN is LOW, PG is high impedance.
B2	SCL	I ² C Clock Line. Used for I ² C communication.
E3, E4	VOUT	Output Voltage. Buck-Boost Output. Connect to output load and C _{OUT} .

Note:

1. Refer to Layout Recommendation section located near the end of the datasheet.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol		Parameter	Min.	Max.	Unit
PVIN/AVIN	PVIN/AVIN Voltage		-0.3	6.5	V
VOUT	VOUT Voltage		-0.3	6.5	V
SW1, SW2	SW Nodes Voltage		-0.3	7.0	V
	Other Pins		-0.3	6.5	V
ESD	Electrostatic Discharge	Human Body Model per JESD22-A114	2	000	V
E3D	Protection Level	Charged Device Model per JESD22-C101	1	000	v
TJ	Junction Temperature		-40	+150	°C
T _{STG}	Storage Temperature		-65	+150	°C
TL	Lead Soldering Tempera	ature, 10 Seconds		+260	°C

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Тур.	Max.	Unit
PVIN	Supply Voltage Range	2.5		5.5	V
I _{OUT}	Output Current ⁽²⁾	0		2.5	А
L	Inductor ⁽⁵⁾		1.0		μH
C _{IN}	Input Capacitance ^(2,3,4,5)	2	47		μF
C _{OUT}	Output Capacitance ^(2,3,4,5)	17	47		μF
T _A	Operating Ambient Temperature	-40		+85	°C
TJ	Operating Junction Temperature	-40		+125	°C

Notes:

2. Depends on input and output voltages. Thermal properties of the device should be taken into consideration; refer to Thermal Consideration in the Application Information section.

3. Typical value reflects the capacitor value needed to meet minimum requirement. Minimum passive component values indicate effective capacitance which includes temperature, voltage de-rating, tolerance, and stability.

Output capacitance affects load transient response and loop phase margin; see Application Information section.
 Refer to Additional Application Information section.

Thermal Properties

Junction-to-ambient thermal resistance is a function of application and board layout. This data is measured with fourlayer 2s2p with vias JEDEC class boards in accordance to JEDEC standard JESD51. Special attention must be paid not to exceed junction temperature $T_{J(max)}$ at a given ambient temperature T_A .

Symbol	Parameter	Min.	Тур.	Max.	Unit
θ_{JA}	Junction-to-Ambient Thermal Resistance ⁽⁶⁾		66		°C/W

Note:

6. See Thermal Considerations in the Application Information section.

Electrical Characteristics⁽⁷⁾

Minimum and maximum values are at PVIN = AVIN = 2.5 V to 5.5 V, $T_A = -40^{\circ}$ C to +85°C. Typical values are at $T_A = 25^{\circ}$ C, PVIN = AVIN = V_{EN} = 3.6 V, VOUT = 3.4 V.⁽⁸⁾

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Power Su	pplies				•	
	Ouriges and Current	PFM Mode, $I_{OUT} = 0 \text{ mA}^{(9)}$		24		
lq	Quiescent Current	PT Mode, I _{OUT} = 0 mA		27		μA
I _{SD}	Shutdown Supply Current	EN = GND, PVIN = 3.6 V		0.5	5.0	μΑ
V _{UVLO}	Under-Voltage Lockout Threshold	Falling PVIN	1.95	2.00	2.05	V
V _{UVHYST}	Under-Voltage Lockout Hysteresis			200		mV
EN, SDA,	SCL					
VIH	HIGH Level Input Voltage		1.1			V
VIL	LOW Level Input Voltage				0.4	V
I _{IN}	Input Bias Current Into Pin	Input Tied to GND or PVIN		0.01	1.00	μA
PG	·	· ·				
V_{PG}	PG LOW	I _{PG} = 5 mA			0.4	V
I _{PG_LK}	PG Leakage Current	V _{PG} = 5 V			1	μA
Switching]	· ·				
f _{SW}	Switching Frequency	PVIN = 3.6 V, T _A = 25°C	1.6	1.8	2.0	MHz
I _{p_LIM}	Peak PMOS Current Limit	PVIN = 3.6 V	4.6	5.2	5.9	Α
Accuracy					•	
V		$\label{eq:PVIN} \begin{array}{l} PVIN = 3.6 \ V, \ Forced \ PWM, \\ I_{OUT} = 0 \ mA, \ VOUT = 3.4 \ V \end{array}$	3.366	3.400	3.434	V
V _{OUT_ACC}	DC Output Voltage Accuracy	$\begin{array}{l} PVIN = 3.6 \text{ V}, \text{ PFM Mode}, \\ I_{OUT} = 0 \text{ mA}, \text{ VOUT} = 3.4 \text{ V} \end{array}$	3.366	3.475	3.563	v

Notes:

7. Refer to Typical Characteristics waveforms/graphs for Closed-Loop data and its variation with input voltage and ambient temperature. Electrical Characteristics reflects Open-Loop steady state data. System Characteristics reflects both steady state and dynamic Close-Loop data associated with the recommended external components.

8. Minimum and Maximum limits are verified by design, test, or statistical analysis. Typical (Typ.) values are not tested, but represent the parametric norm.

9. Device is not switching.

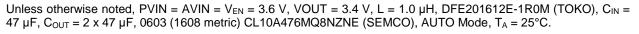
System Characteristics

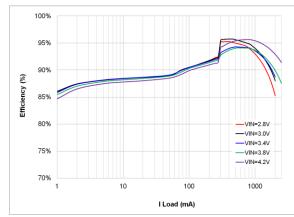
The following table is verified by design and bench test while using circuit of Figure 1 with the following external components: L = 1.0 μ H, DFE201612E-1R0M (TOKO), C_{IN} = 47 μ F, C_{OUT} = 2 x 47 μ F, 0603 (1608 metric) CL10A476MQ8NZNE (SEMCO). Typical values are at T_A = 25°C, PVIN = AVIN = V_{EN} = 3.6 V, VOUT = 3.4 V. These parameters are not verified in production.

Symbol	Parameter		Min.	Тур.	Max.	Unit	
V _{OUT_ACC}	Total Accuracy (Includes DC accuracy and load transient) ⁽¹⁰⁾			±5		%	
ΔV _{OUT}	Load Regulation	I _{OUT} = 0.4 A to 2.5 A, PVIN = 3.6 V		-0.20		%/A	
ΔV _{OUT}	Line Regulation	$3.0 \text{ V} \le \text{PVIN} \le 4.2 \text{ V}, \text{ I}_{\text{OUT}} = 1.5 \text{ A}$		-0.06		%/V	
		PVIN = 4.2 V, VOUT = 3.4 V, I _{OUT} = 1 A, PWM Mode		4			
$V_{\text{OUT}_\text{RIPPLE}}$	Ripple Voltage	PVIN = 3.6 V, VOUT = 3.4 V, I _{OUT} = 100 mA, PFM Mode		22		mV	
		$\label{eq:VIN} \begin{array}{l} PVIN = 3.0 \ V, \ VOUT = 3.4 \ V, \\ I_{OUT} = 1 \ A, \ PWM \ Mode \end{array}$		14			
		$\label{eq:VIN} \begin{array}{l} PVIN = 3.0 \ V, \ VOUT = 3.4 \ V, \\ I_{OUT} = 50 \ mA, \ PFM \end{array}$		90			
		PVIN = 3.0 V, VOUT = 3.4 V, I _{OUT} = 500 mA, PWM		96			
η	Efficiency	$\label{eq:VIN} \begin{array}{l} PVIN = 3.8 \ V, \ VOUT = 3.4 \ V, \\ I_{OUT} = 50 \ mA, \ PFM \end{array}$		90		%	
		PVIN = 3.8 V, VOUT = 3.4 V, I _{OUT} = 600 mA, PWM		94			
		$\label{eq:VIN} \begin{array}{l} PVIN = 3.4 \ V, \ VOUT = 3.4 \ V, \\ I_{OUT} = 300 \ mA, \ PWM \end{array}$		94			
T _{SS}	Soft-Start	EN HIGH to 95% of Target VOUT, $I_{OUT} = 68 \text{ mA}$		260		μs	
		$\begin{array}{l} PVIN=3.4 \; V, \; I_{OUT}=0.5 \; A \Leftrightarrow 1 \; A, \\ T_{R}=T_{F}=1 \; \mu s \end{array}$	±45				
ΔV_{OUT_LOAD}	Load Transient	$\begin{array}{l} PVIN=3.4 \; V, \; I_{OUT}=0.5 \; A \Leftrightarrow \\ 2.0 \; A, \; T_{R}=T_{F}=1 \; \mu s, \; Pulse \; Width \\ = \; 577 \; \mu s \end{array}$		±125		mV	
$\Delta V_{\text{OUT_LINE}}$	Line Transient	$\begin{array}{l} PVIN=3.0 \; V \Leftrightarrow 3.6 \; V, \\ T_{R}=T_{F}=10 \; \mu s, \; I_{OUT}=1 \; A \end{array}$		±60		mV	

10. Load transient is from 0.5 A <-> 1 A.

Typical Characteristics







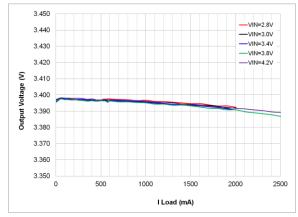
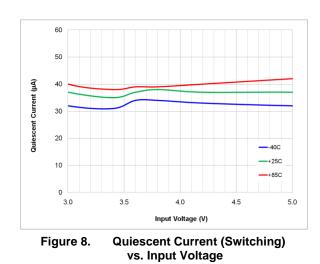


Figure 6. Output Regulation vs. Load, FPWM Mode



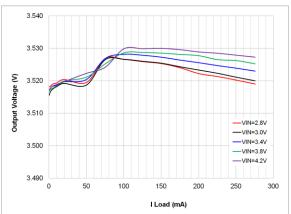


Figure 5. Output Regulation vs. Load

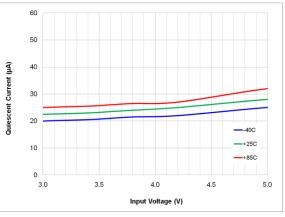


Figure 7. Quiescent Current (No Switching) vs. Input Voltage

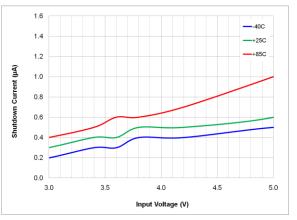
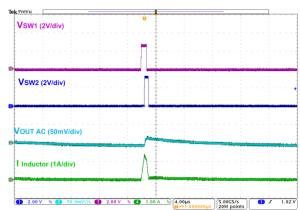


Figure 9. Shutdown Current vs. Input Voltage

Typical Characteristics (Continued)

Unless otherwise noted, PVIN = AVIN = V_{EN} = 3.6 V, VOUT = 3.4 V, L = 1.0 µH, DFE201612E-1R0M (TOKO), C_{IN} = 47 µF, C_{OUT} = 2 x 47 µF, 0603 (1608 metric) CL10A476MQ8NZNE (SEMCO), AUTO Mode, T_A = 25°C.



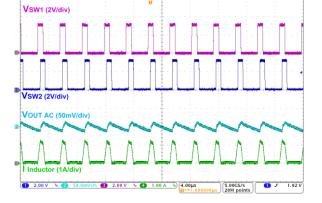


Figure 10. Output Ripple, VIN = 2.8 V, I_{OUT} = 20 mA, Boost Operation

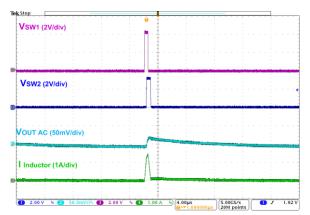


Figure 12. Output Ripple, VIN = 4.2 V, I_{OUT} = 20 mA, Buck Operation

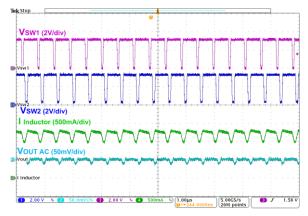


Figure 14. Output Ripple, VIN = 3.3 V, I_{OUT} = 1000 mA, Buck-Boost Operation

Figure 11. Output Ripple, VIN = 3.3 V, I_{OUT} = 200 mA, Buck-Boost Operation

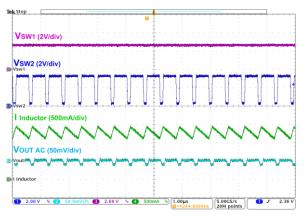


Figure 13. Output Ripple, VIN = 2.5 V, I_{OUT} = 1000 mA, Boost Operation

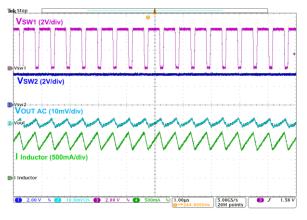
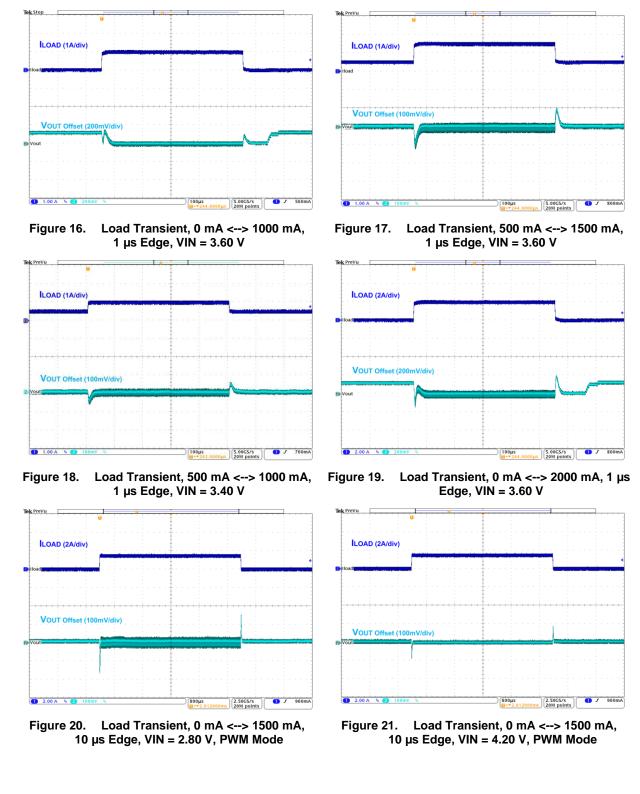
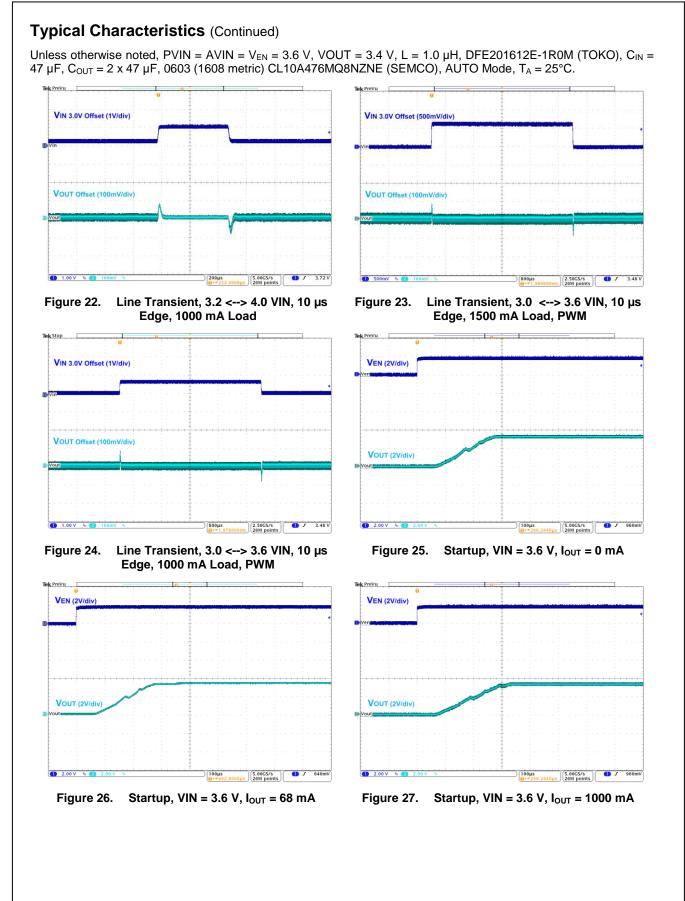


Figure 15. Output Ripple, VIN = 4.5 V, I_{OUT} = 1000 mA, Buck Operation

Typical Characteristics (Continued)

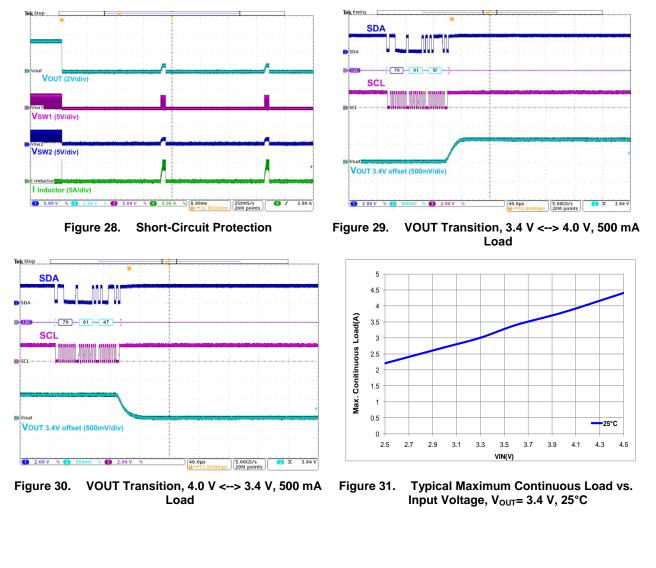
Unless otherwise noted, PVIN = AVIN = V_{EN} = 3.6 V, VOUT = 3.4 V, L = 1.0 µH, DFE201612E-1R0M (TOKO), C_{IN} = 47 µF, C_{OUT} = 2 x 47 µF, 0603 (1608 metric) CL10A476MQ8NZNE (SEMCO), AUTO Mode, T_A = 25°C.





Typical Characteristics (Continued)

Unless otherwise noted, PVIN = AVIN = V_{EN} = 3.6 V, VOUT = 3.4 V, L = 1.0 µH, DFE201612E-1R0M (TOKO), C_{IN} = 47 µF, C_{OUT} = 2 x 47 µF, 0603 (1608 metric) CL10A476MQ8NZNE (SEMCO), AUTO Mode, T_A = 25°C.



Application Information

Functional Description

FAN49103 is a fully integrated synchronous, full bridge DC-DC converter that can operate in buck operation (during high PVIN), boost operation (for low PVIN) and a combination of buck-boost operation when PVIN is close to the target VOUT value. The PWM/PFM controller switches automatically and seamlessly between buck, buck-boost and boost modes.

The FAN49103 uses a four-switch operation during each switching period when in the buck-boost mode. Mode operation is as follows: referring to the power drive stage shown in Figure 32 if PVIN is greater than target VOUT, then the converter is in buck mode: Q3 is ON and Q4 is OFF continuously leaving Q1, Q2 to operate as a current-mode controlled PWM converter. If PVIN is lower than target VOUT then the converter is in boost mode with Q1 ON and Q2 OFF continuously, while leaving Q3, Q4 to operate as a current-mode boost converter. When PVIN is near VOUT, the converter goes into a 3-phase operation in which combines a buck phase, a boost phase and a reset phase; all switches are switching to maintain an average inductor volt-second balance.

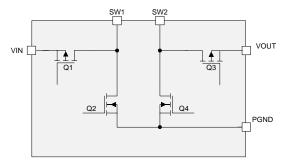


Figure 32. Simplified Block Diagram

PFM/PWM Mode

The FAN49103 uses a current-mode modulator to achieve smooth transitions between PWM and PFM operation. In Pulsed Frequency Modulation (PFM), frequency is reduced to maintain high efficiency. During PFM operation, the converter positions the output voltage typically 75 mV higher than the nominal output voltage during PWM operation, allowing additional headroom for voltage drop during a load transient from light to heavy load. As the load increased from light loads, the converter enters PWM operation typically at 300 mA of current load. The converter switching frequency is typically 1.8 MHz during PWM operation for moderate to heavy load currents.

PT (Pass-Through) Mode

In Pass-Through mode, all of the switches are not switching and VOUT tracks PVIN (VOUT = PVIN – I_{OUT} *(Q1_{RDSON} + Q3_{RDSON} +L_{DCR}) In PT mode only Over-Temperature (OTP) and Under Voltage Lockout (UVLO) protection circuits are activated. There is no Over-Current Protection (OCP) in PT mode.

Shutdown and Startup

When the EN pin is LOW, the IC is shut down, all internal circuits are off, and the part draws very little current. During shutdown, VOUT is isolated from PVIN. Raising EN pin activates the device and begins the softstart cycle. During soft-start, the modulator's internal reference is ramped slowly to minimize surge currents on the input and prevent overshoot of the output voltage. If VOUT fails to reach target VOUT value after 1ms, a FAULT condition is declared.

Over-Temperature (OTP)

The regulator shuts down when the die temperature exceeds 150°C. Restart occurs when the IC has cooled by approximately 20°C.

Output Discharge

When the regulator is disabled and driving the EN pin LOW, a 230 Ω internal resistor is activated between VOUT and GND. The Output Discharge is not activated during a FAULT state condition.

Over-Current Protection (OCP)

If the peak current limit is activated for a typical 700 $\mu s,$ a FAULT state is generated, so that the IC protects itself as well as external components and load.

FAULT State

The regulator enters the FAULT state under any of the following conditions:

- VOUT fails to achieve the voltage required after soft-start.
- Peak current limit triggers.
- OTP or UVLO are triggered.

Once a FAULT is triggered, the regulator stops switching and presents a high-impedance path between PVIN and VOUT. After waiting 30 ms, a restart is attempted.

Power Good

PG, an open-drain output, is LOW during FAULT state and HIGH for Power Good.

The PG pin is provided for signaling the system when the regulator has successfully completed soft-start and no FAULTs have occurred. PG pin also functions as a warning flag for high die temperature and overload conditions.

- PG is released HIGH when the soft-start sequence is successfully completed.
- PG is pulled LOW when a FAULT is declared.

Any FAULT condition causes PG to be de-asserted.

Thermal Considerations

For best performance, the die temperature and the power dissipated should be kept at moderate values. The maximum power dissipated can be evaluated based on the following relationship:

$$P_{D(\max)} = \left\{ \frac{T_{J(\max)} - T_A}{\Theta_{JA}} \right\}$$
(1)

where $T_{J(max)}$ is the maximum allowable junction temperature of the die; T_A is the ambient operating temperature; and θ_{JA} is dependent on the surrounding PCB layout and can be improved by providing a heat sink of surrounding copper ground.

The addition of backside copper with through-holes, stiffeners, and other enhancements can help reduce θ_{JA} . The heat contributed by the dissipation of devices nearby must be included in design considerations. Following the layout recommendation may lower the θ_{JA} .

I²C Interface

The FAN49103's serial interface is compatible with Standard, Fast, Fast Plus, and HS Mode I²C-Bus® specifications. The SCL line is an input and its SDA line is a bi-directional open-drain output; it can only pull down the bus when active. The SDA line only pulls LOW during data reads and when signaling ACK. All data is shifted in MSB (bit 7) first.

I²C Slave Address

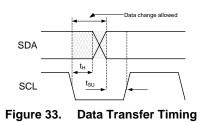
In hex notation, the slave address assumes a 0 LS Bit. The hex slave address is E0.

Table 1. I²C Slave Address

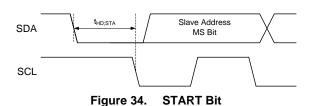
Her					Bits			
Hex	7	6	5	4	3	2	1	0
E0	1	1	1	0	0	0	0	R/W

Bus Timing

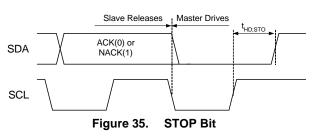
As shown in Figure 33, data is normally transferred when SCL is LOW. Data is clocked in on the rising edge of SCL. Typically, data transitions shortly at or after the falling edge of SCL to allow ample time for the data to set up before the next SCL rising edge.



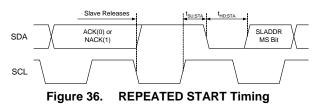
Each bus transaction begins and ends with SDA and SCL HIGH. A transaction begins with a START condition, which is defined as SDA transitioning from 1 to 0 with SCL HIGH, as shown in Figure 34.



A transaction ends with a STOP condition, which is defined as SDA transitioning from 0 to 1 with SCL HIGH, as shown in Figure 35.



During a read from the FAN49103, the master issues a REPEATED START after sending the register address, and before resending the slave address. The REPEATED START is a 1 to 0 transition on SDA while SCL is HIGH, as shown in Figure 36.



High-Speed (HS) Mode

The protocols for High-Speed (HS), Low-Speed (LS), and Fast-Speed (FS) Modes are identical; except the bus speed for HS mode is 3.4 MHz. HS Mode is entered when the bus master sends the HS master code 00001XXX after a START condition. The master code is sent in Fast or Fast-Plus Mode (less than 1 MHz clock); slaves do not ACK this transmission.

The master generates a REPEATED START condition (Figure 34) that causes all slaves on the bus to switch to HS Mode. The master then sends I2C packets, as described above, using the HS Mode clock rate and timing.

The bus remains in HS Mode until a STOP bit (Figure 35) is sent by the master. While in HS Mode, packets are separated by REPEATED START conditions (Figure 36).

Read and Write Transactions

defined as

The following figures outline the sequences for data read and write. Bus control is signified by the shading of the packet,

Master Drives Bus and

Slave Drives Bus . All addresses and data are MSB first.

Table 2. I²C Bit Definitions for Figure 37 & Figure 38

Symbol	Definition
R	REPEATED START, see Figure 36
Р	STOP, see Figure 35
S	START, see Figure 34
A	ACK. The slave drives SDA to 0 to acknowledge the preceding packet.
Ā	NACK. The slave sends a 1 to NACK the preceding packet.
R	REPEATED START, see Figure 36.
Р	STOP, see Figure 35.



Figure 37. Write Transaction

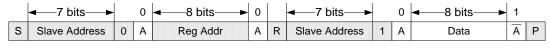


Figure 38. Read Transaction

Register Description

Table 3. Register Table

Hex Address	Name	Function
00	SOFT-RESET	Resets all registers to default values.
01	VOUT_REF	Set the target regulation point of VOUT.
02	CONTROL	PT and MODE control.
40	Manufacturer_ID	Read-only register identifies vendor and device type.
41	Device_ID	Read-only register identifies die ID.

FAN49103
)3 — 2.5 A
, ₽, 1
00
MHz, 1
TinyP
OWER TM
I²C
I ² C Buck-Boost Regula
Regulator

t Na	ame	Value			Description	
FT-RESE			Register Add	tress: 00	•	
Res	erved	0000000				
Soft	_reset	0	Write 1 to rese	t all registers.		
JT_REF	R/V	V	Register Add	dress: 01		
Res	erved	0				
			Sets the target	regulation point for VO	UT.	1
			HEX	VOUT	HEX	VOUT
			00 - 2E	Reserved	47	3.400
			2F	2.800	48	3.425
			30	2.825	49	3.450
			31	2.850	4A	3.475
			32	2.875	4B	3.500
			33	2.900	4C	3.525
			34	2.925	4D	3.550
			35	2.950	4E	3.575
			36	2.975	4F	3.600
			37	3.000	50	3.625
	Ref_dac_code	1000111	38	3.025	51	3.650
Ref_d			39	3.050	52	3.675
			3A	3.075	53	3.700
			3B	3.100	54	3.725
			3C	3.125	55	3.750
			3D	3.150	56	3.775
			3E	3.175	57	3.800
			3F	3.200	58	3.825
			40	3.225	59	3.850
			41	3.250	5A	3.875
			42	3.275	5B	3.900
			43	3.300	5C	3.925
			44	3.325	5D	3.950
			45	3.350	5E	3.975
			46	3.375	5F 60 - 7F	4 Peconvod
NTROL	R/V	v	Register Add		00 - 7F	Reserved
-	erved	0000	Register Add	1033. 02		
1.03	0.000		Enables Pass-	Through mode.		
1			Code		Mode	
i2c_	_pt_in	0	0	Regulated output (Roo	st, Buck or Buck-Boost)	
			1	Pass-Through enabled		
+					as Pass-Through is not er	nabled.
1			Code		Mode	
i2c_m	ode_in	0	0	Auto PWM - PFM mo		
1			1	Forced PWM mode e		
Res	erved	00		. croca i vivi mode e		
	er_ID R		Register Add	dress: 40		

Table 4. Recommended Capacitors

Capac	itor	Part Number	Vendor	Value	Case Size	Rating
CIN	I	CL10A476MQ8NZNE	SEMCO	47 µF	0603 (1608 Metric)	6.3 V
C _{OU}	т	CL10A476MQ8NZNE	SEMCO	2 x 47 µF	0603 (1608 Metric)	6.3 V

Output Capacitance (COUT) and Input Capacitance (CIN) Stability

The effective capacitance (C_{EFF}) of small, high-value, ceramic capacitors will decrease as bias voltage increases. FAN49103 is guaranteed for stable operation with the minimum value of 17 μ F (C_{EFF(MIN)}) output capacitance when using a 1 μ H value inductor and a minimum value of 13 μ F (C_{EFF(MIN)}) output capacitance when using a 0.47 μ H value inductor. Furthermore, FAN49103 is guaranteed for stable operation with the minimum value of 2 μ F (C_{EFF(MIN)}) input capacitance. De-rating factors should be taken into consideration to ensure selected components meet minimum requirement.

Table 5.	Minimum	C _{EFF} ⁽¹¹	⁾ Required	for	Stability
----------	---------	---------------------------------	-----------------------	-----	-----------

VOUT (V)	I _{LOAD} (A)	Inductor Value	C _{EFF(MIN)}
3.4 V	0 – 2.5 A	1.0 µH	17 µF
3.4 V	0 – 2.5 A	0.47 µH	13 µF

Note:

11. C_{EFF} is defined as the capacitance value during operating conditions and not the capacitor value. A capacitor varies with manufacturer, material, case size, voltage rating and temperature.

Inductor Selection

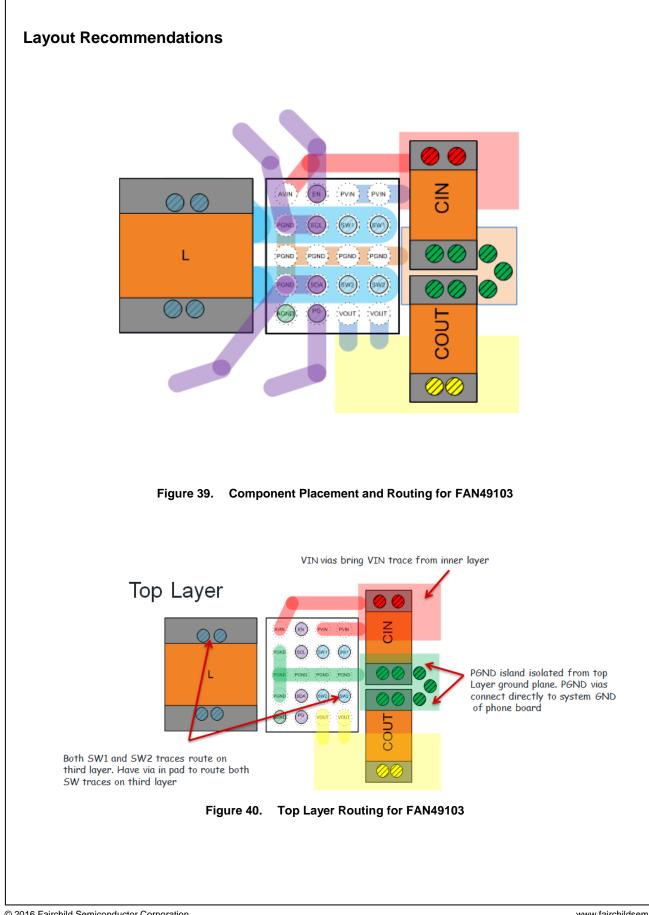
Recommended nominal inductance value is $1.0 \,\mu$ H. An inductor value of $0.47 \,\mu$ H can be used but higher peak currents could lead to lower efficiency; however, transient response performance may be improved. FAN49103 employs peak current limiting and the peak inductor current can reach typically 5.2 A for a short duration during overload conditions. Therefore, current saturation value should be taken into consideration when choosing an inductor.

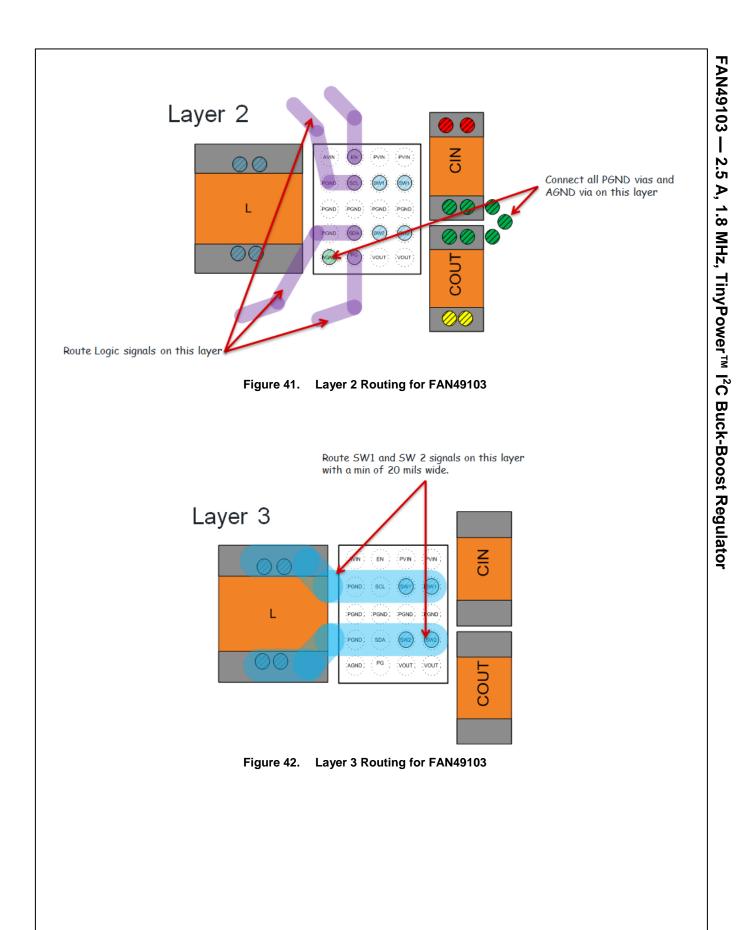
Table 6. Recommended Inductors

Part Number	Vendor	Value	Dimension	Isat	DCR
DFE201610E1R0M	токо	1.0 µH	2.0 mm x 1.6 mm x 1.0 mm	3.9 A	48 mΩ
DFE201612E1R0M			2.0 mm x 1.6 mm x 1.2 mm	4.4 A	40 mΩ
DFE201610ER47M		0.47 μH ⁽¹²⁾ (Optional)	2.0 mm x 1.6 mm x 1.0 mm	5.3 A	26 mΩ
DFE201612ER47M			2.0 mm x 1.6 mm x 1.2 mm	6.1 A	20 mΩ

Note:

12. When using 0.47 μH inductor value, one 47 μF (CL10A476MQ8NZNE) capacitor can be used at the output of the regulator.

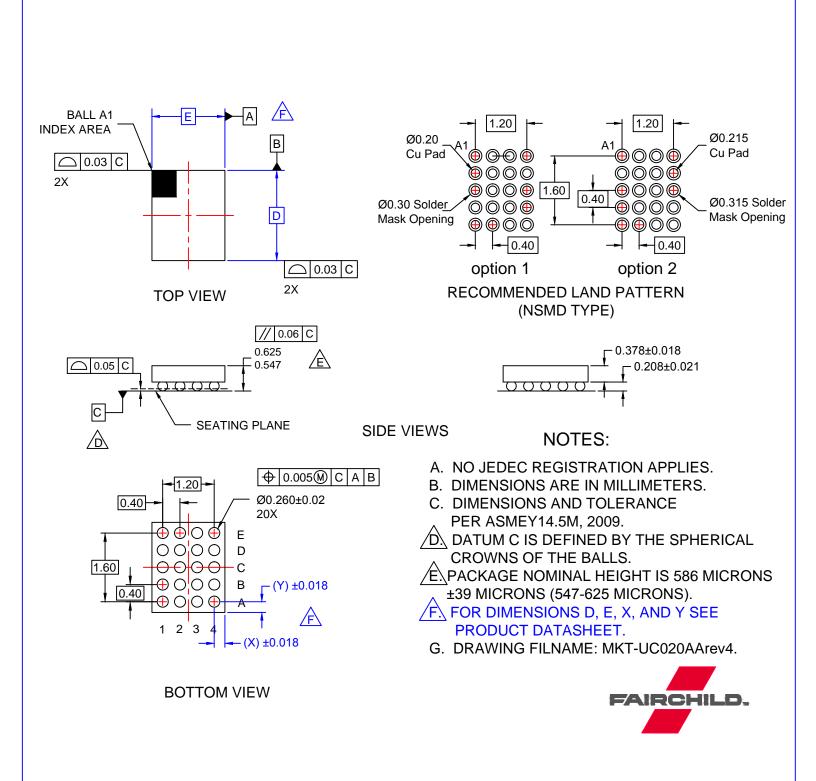




Physical Dimensions

This table information applies to the Package drawing on the following page.

Product	D	E	Х	Y
FAN49103AUC340X	2.015 ±0.030	1.615 ±0.030	0.2075	0.2075



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